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PicoZed 7015/7030 SOM

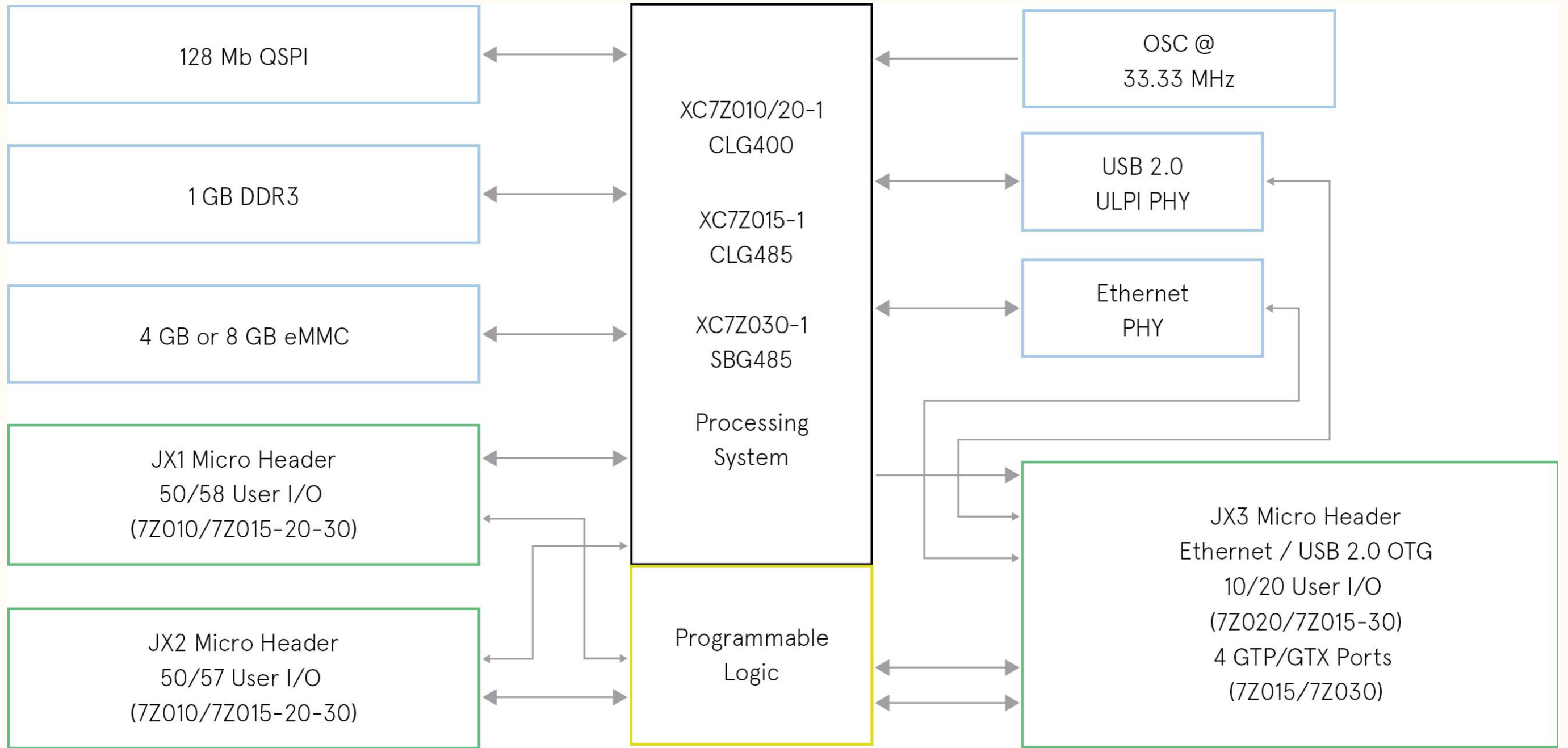
Revision E

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AVNET Avnet Engineering Services				
Project Name:	PicoZed 7015/7030 SOM	PCB Rev:	E	
Doc Num:	SCH-PZ2SOM	BOM:	01	
Date:	12/18/2017	Variant:	01	
Time:	11:06:36 AM	Sheet:	1 of 12	
Sheet Title:	01 - Lead Sheet.SchDoc		Size:	B



Zynq PS DDR - Bank 502

UIG
XC7Z015-1CLG485C

BANK 502

- PS_DDR_DQ0_502
- PS_DDR_DQ1_502
- PS_DDR_DQ2_502
- PS_DDR_DQ3_502
- PS_DDR_DQ4_502
- PS_DDR_DQ5_502
- PS_DDR_DQ6_502
- PS_DDR_DQ7_502
- PS_DDR_DQ8_502
- PS_DDR_DQ9_502
- PS_DDR_DQ10_502
- PS_DDR_DQ11_502
- PS_DDR_DQ12_502
- PS_DDR_DQ13_502
- PS_DDR_DQ14_502
- PS_DDR_DQ15_502
- PS_DDR_DQ16_502
- PS_DDR_DQ17_502
- PS_DDR_DQ18_502
- PS_DDR_DQ19_502
- PS_DDR_DQ20_502
- PS_DDR_DQ21_502
- PS_DDR_DQ22_502
- PS_DDR_DQ23_502
- PS_DDR_DQ24_502
- PS_DDR_DQ25_502
- PS_DDR_DQ26_502
- PS_DDR_DQ27_502
- PS_DDR_DQ28_502
- PS_DDR_DQ29_502
- PS_DDR_DQ30_502
- PS_DDR_DQ31_502

- PS_DDR_A0_502
- PS_DDR_A1_502
- PS_DDR_A2_502
- PS_DDR_A3_502
- PS_DDR_A4_502
- PS_DDR_A5_502
- PS_DDR_A6_502
- PS_DDR_A7_502
- PS_DDR_A8_502
- PS_DDR_A9_502
- PS_DDR_A10_502
- PS_DDR_A11_502
- PS_DDR_A12_502
- PS_DDR_A13_502
- PS_DDR_A14_502

- PS_DDR_DQS_P0_502
- PS_DDR_DQS_N0_502
- PS_DDR_DQS_P1_502
- PS_DDR_DQS_N1_502
- PS_DDR_DQS_P2_502
- PS_DDR_DQS_N2_502
- PS_DDR_DQS_P3_502
- PS_DDR_DQS_N3_502

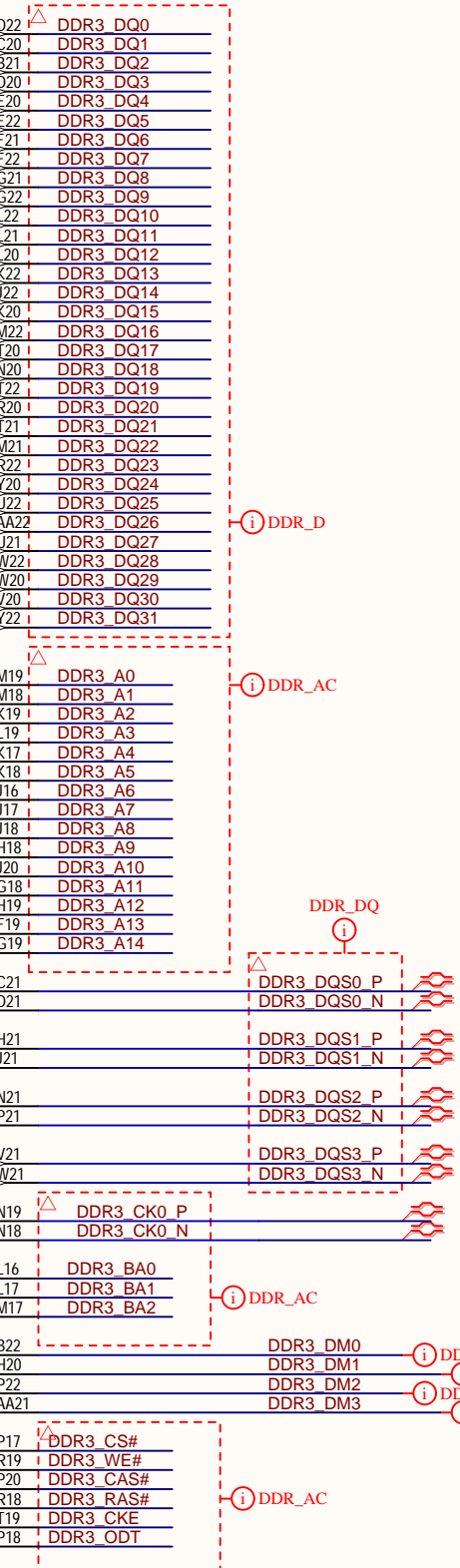
- PS_DDR_CK_P_502
- PS_DDR_CK_N_502

- PS_DDR_DM0_502
- PS_DDR_DM1_502
- PS_DDR_DM2_502
- PS_DDR_DM3_502

- PS_DDR_CS_B_502
- PS_DDR_WE_B_502
- PS_DDR_CAS_B_502
- PS_DDR_RAS_B_502
- PS_DDR_CKE_502
- PS_DDR_ODT_502

- PS_DDR_DRST_B_502
- PS_DDR_VRP_502
- PS_DDR_VRN_502

IC SOC CORTEX-A9, Zynq-7000, 485BGA



- DDR3_D_BLA1(1) DDR3_DQ[7..0]
- DDR3_D_BLA1(1) DDR3_DQ[15..8]
- DDR3_D_BLA1(1) DDR3_DQ[23..16]
- DDR3_D_BLA1(1) DDR3_DQ[31..24]

DDR_D

DDR_AC

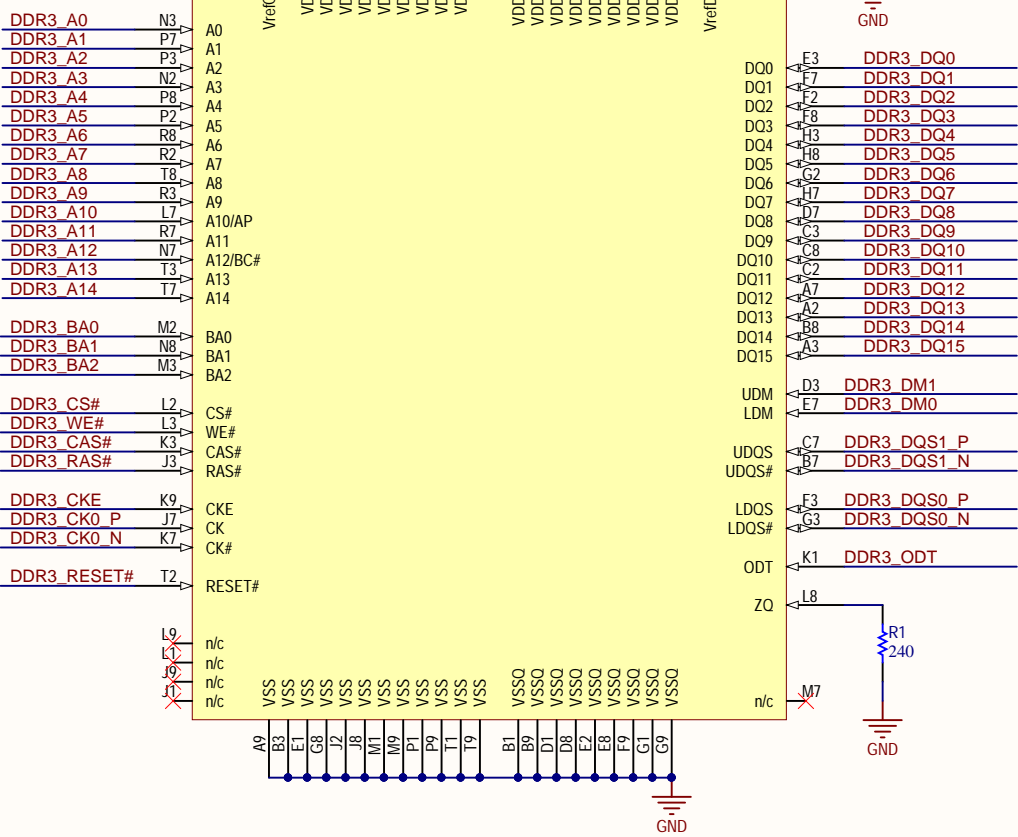
DDR_DQ

DDR_AC

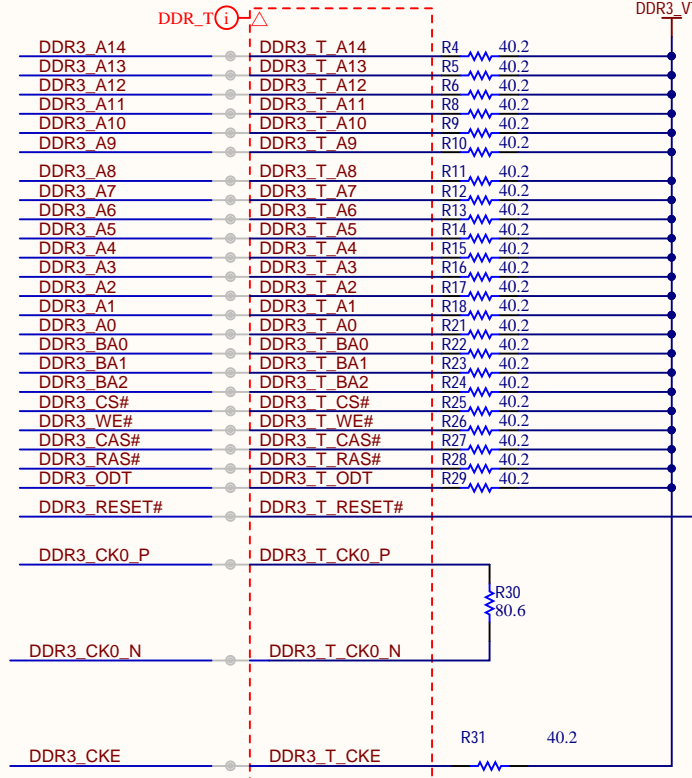
DDR_AC

Layout Note:
DDR3 trace lengths must include Zynq package flight times. See UG933 and Layout Guidelines.

Layout Note:
DDR3 target trace impedances are as follows:
Single Ended Signals = 40 ohms
Differential Signals = 80 ohms

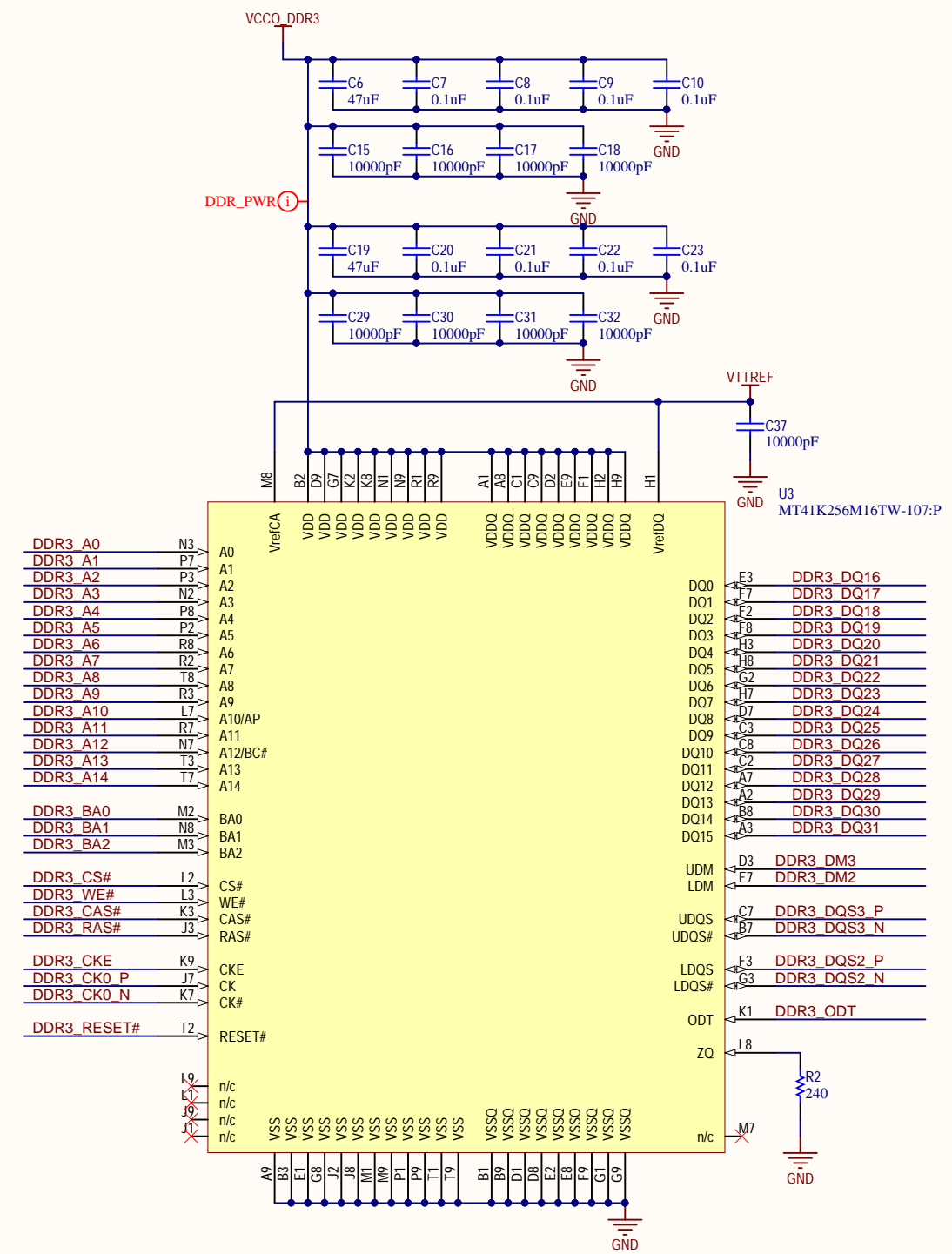


Layout Note:
Use Fly-by routing and termination for DDR3 control signals. Resistors should be placed past the last memory IC & as close to the device as possible.

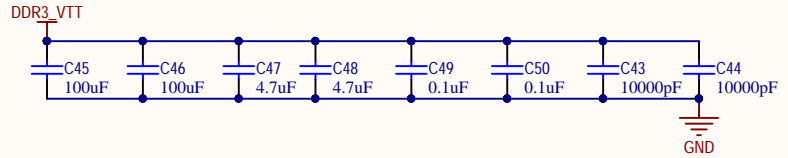
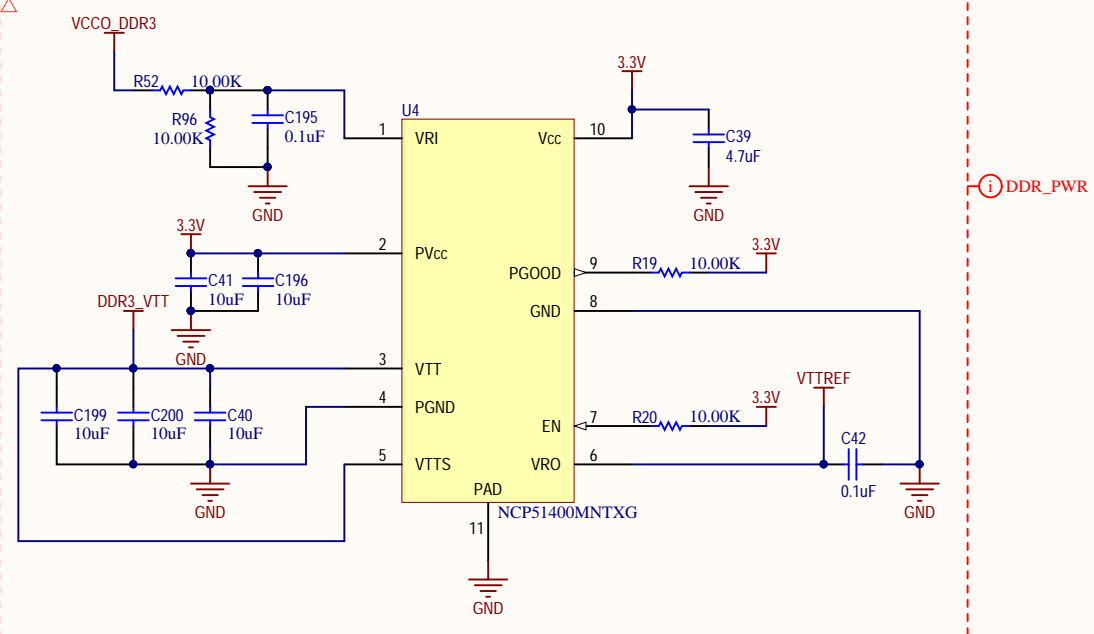


NOTE:
RESET# requires a Pull Down resistor through FPGA Configuration. See UG933p62 and Answer Record 55616.

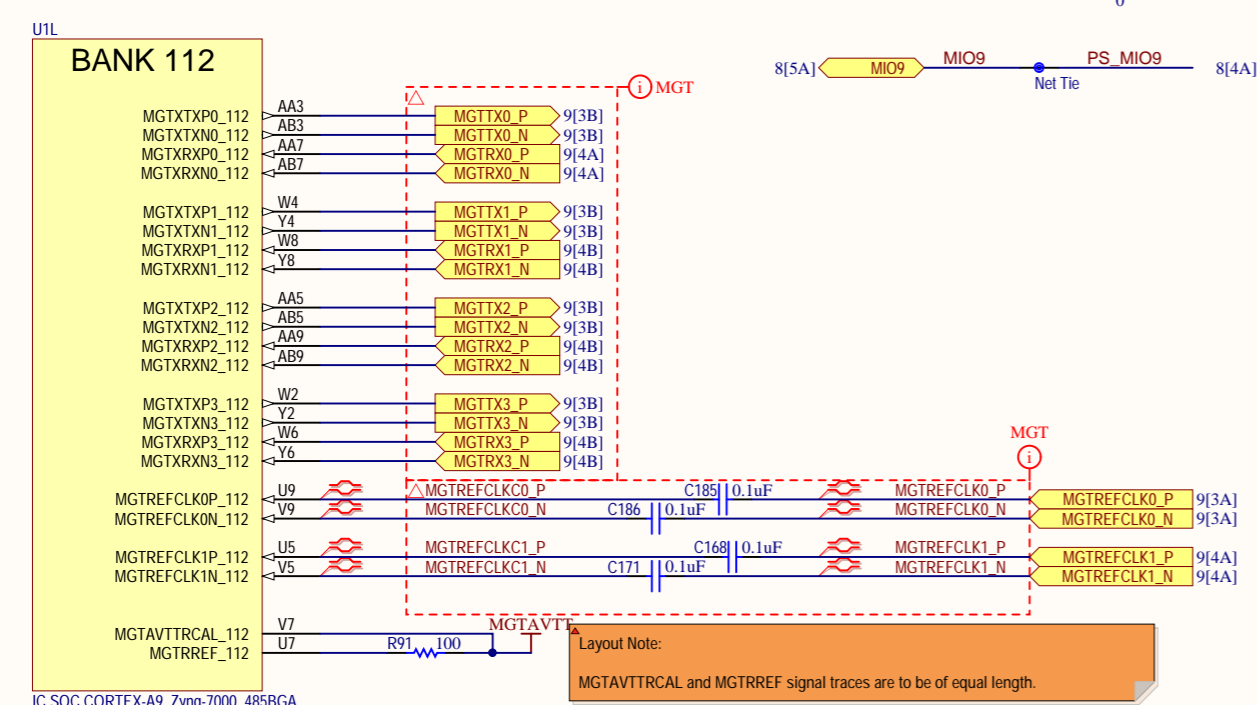
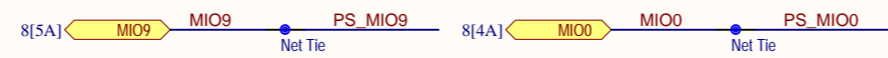
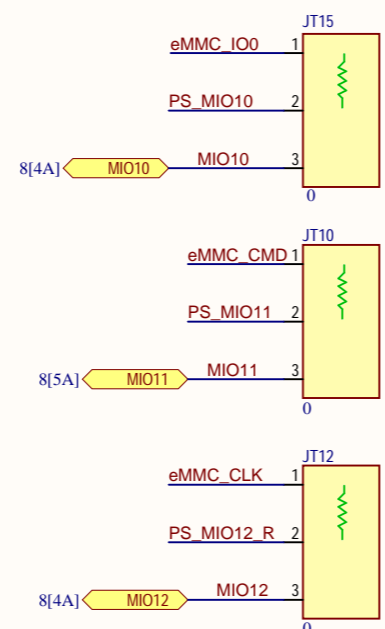
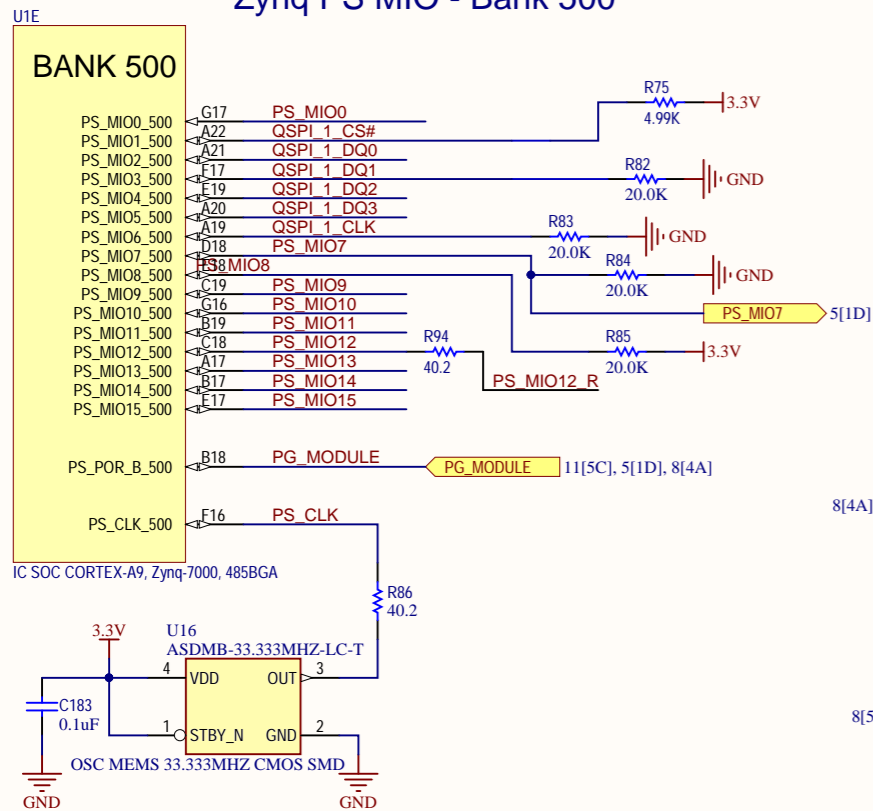
DDR3



DDR3 Termination Supply

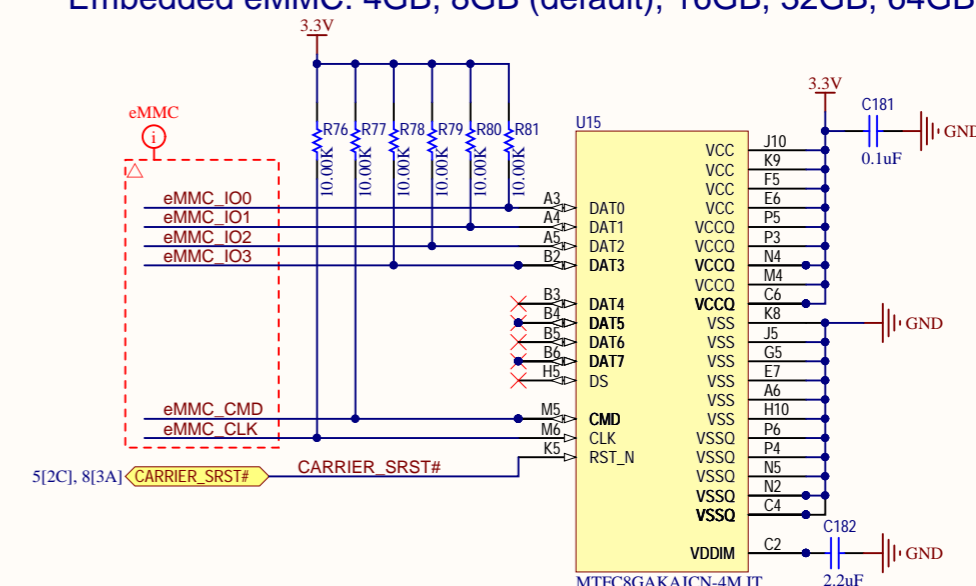


Zynq PS MIO - Bank 500

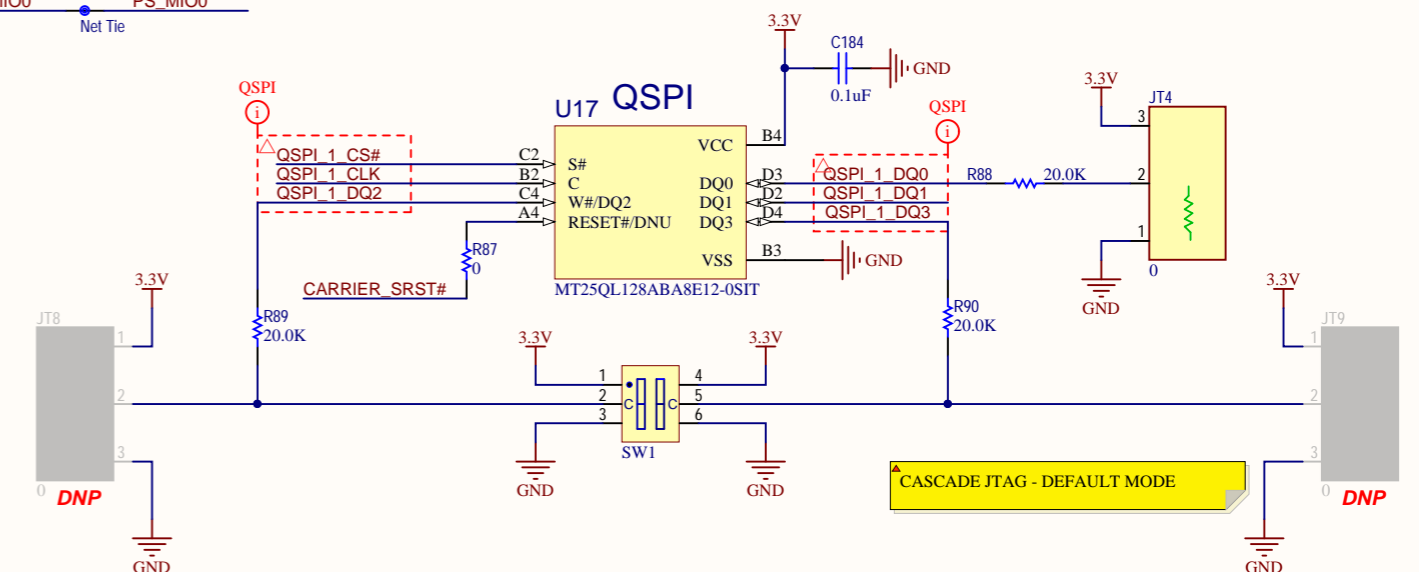


Layout Note:
MGTAVTT and MGTREFREF signal traces are to be of equal length.

Embedded eMMC: 4GB, 8GB (default), 16GB, 32GB, 64GB

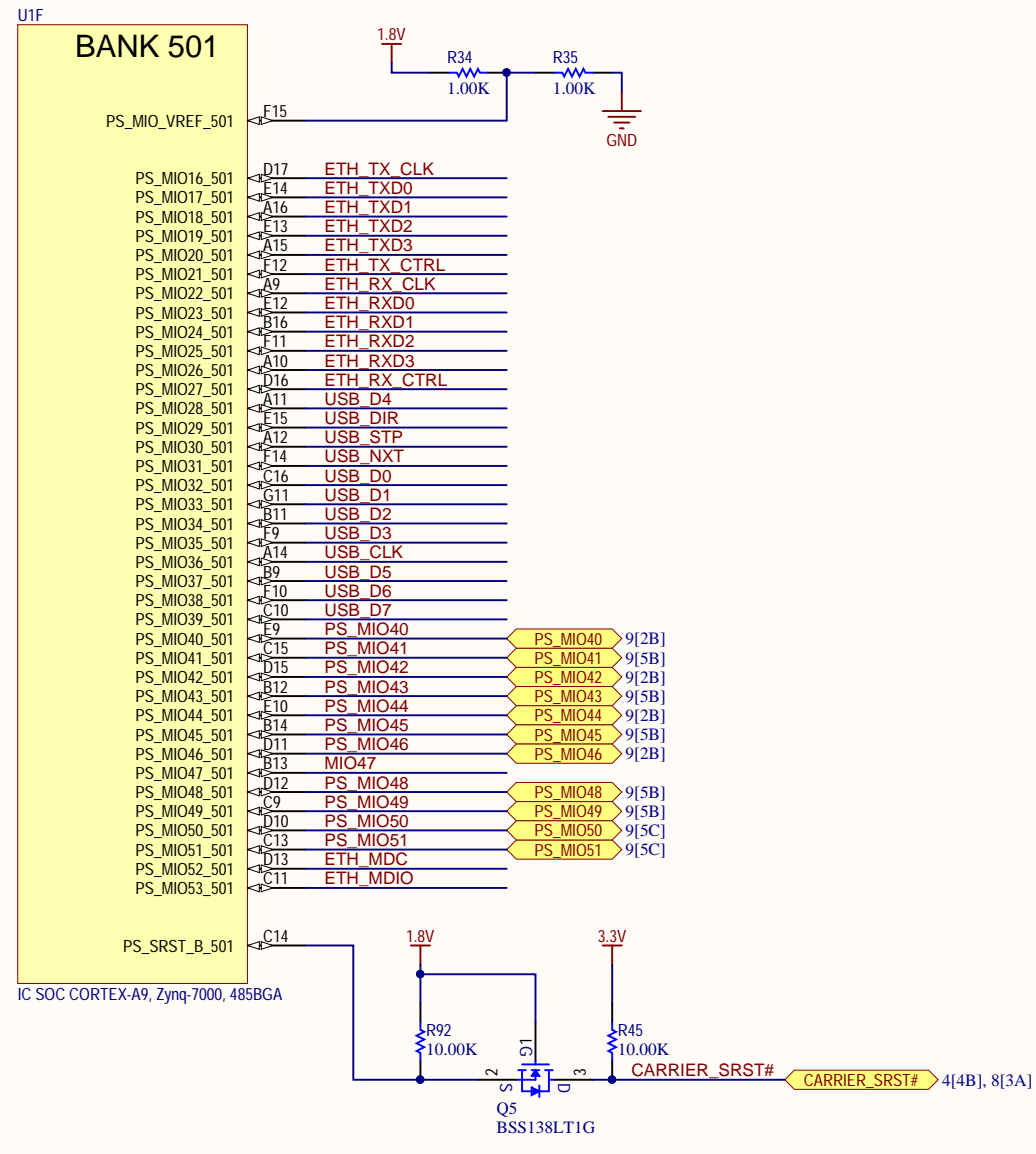


This eMMC footprint is based on the 169-ball WFBGA 14.0mm x 18.0mm x 0.8mm Micron package. The footprint is compatible with the 153-ball WFBGA 11.5mm x 13.0mm x 0.8mm, which is what is populated. See the Hardware User Guide for a conversion table

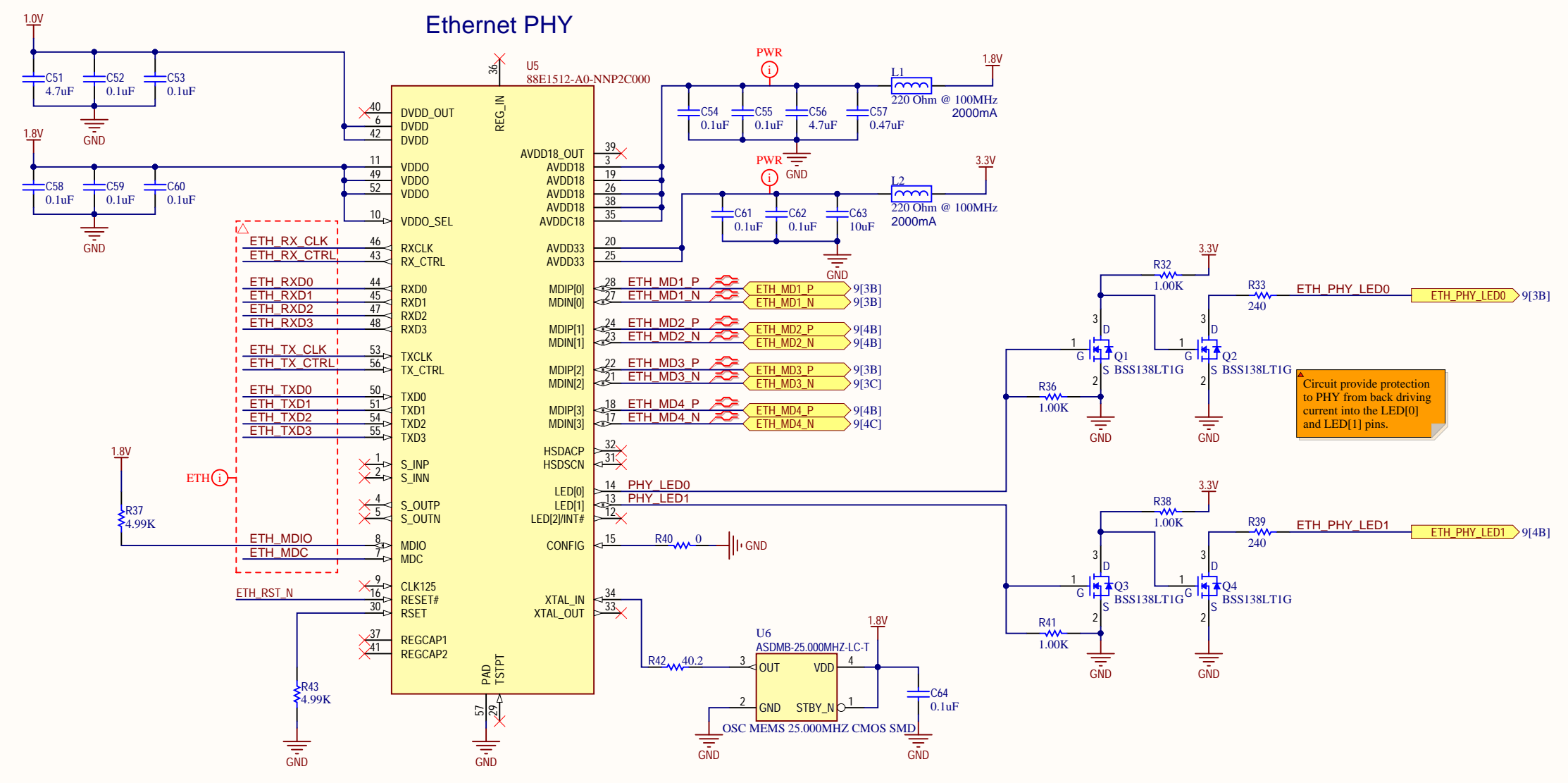


CASCADE JTAG - DEFAULT MODE

Zynq PS MIO - Bank 501

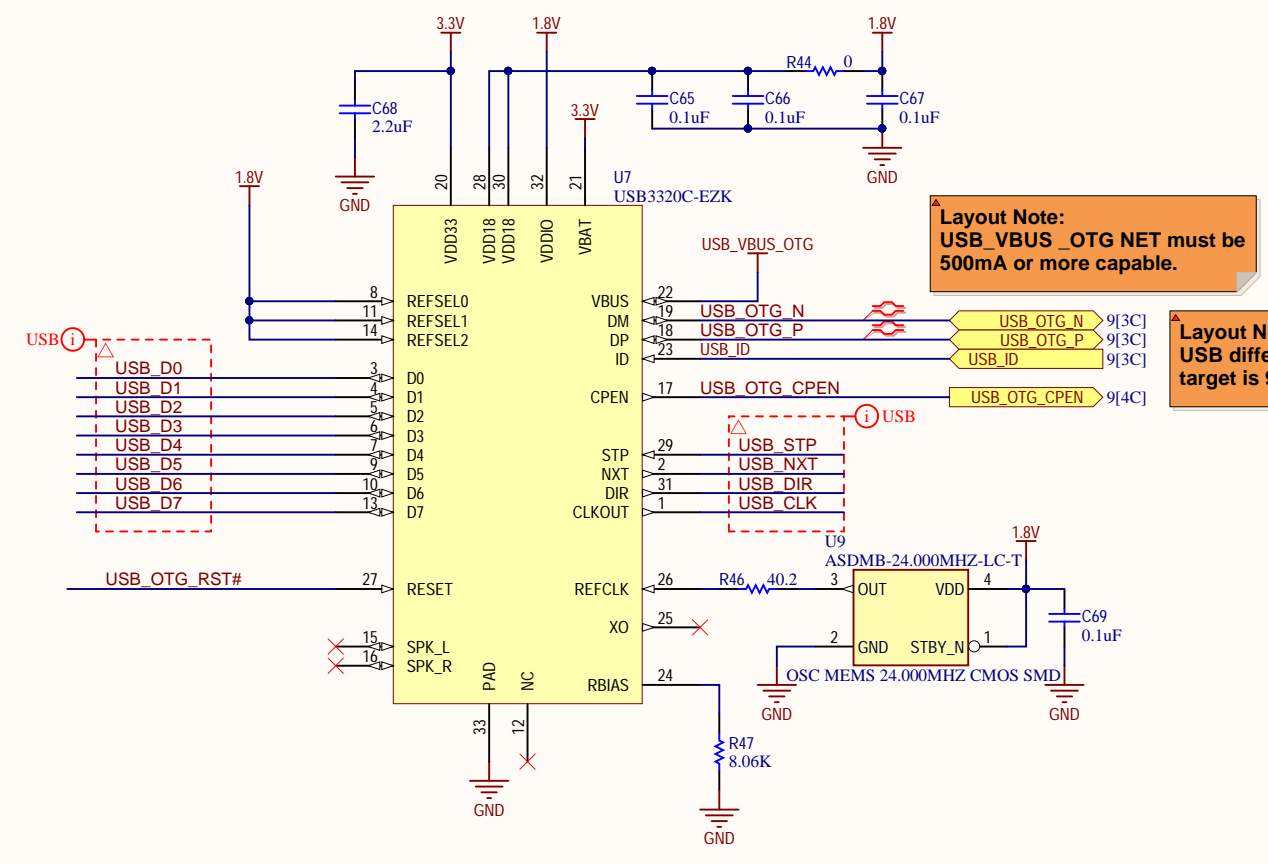


Ethernet PHY



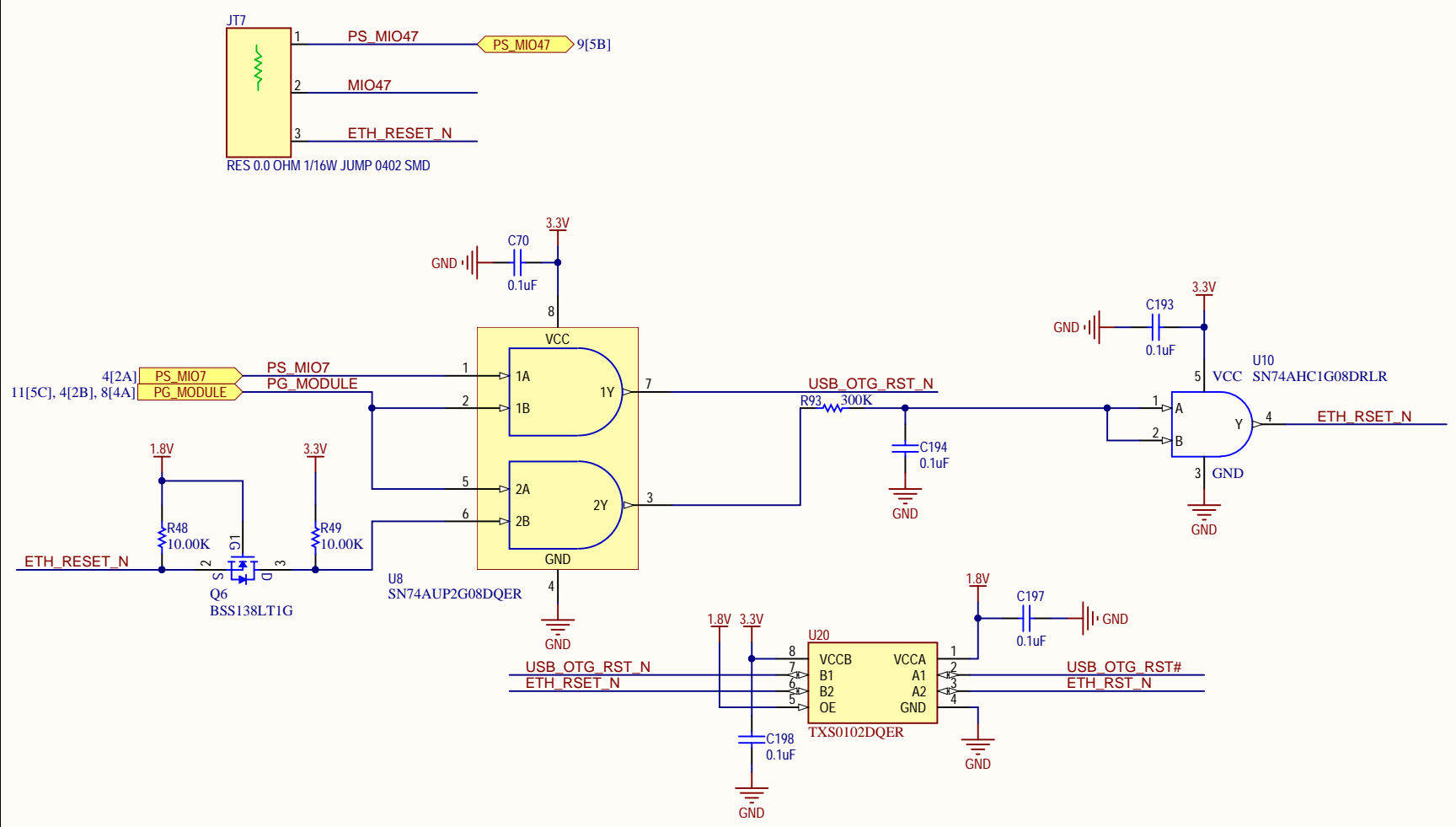
Circuit provide protection to PHY from back driving current into the LED[0] and LED[1] pins.

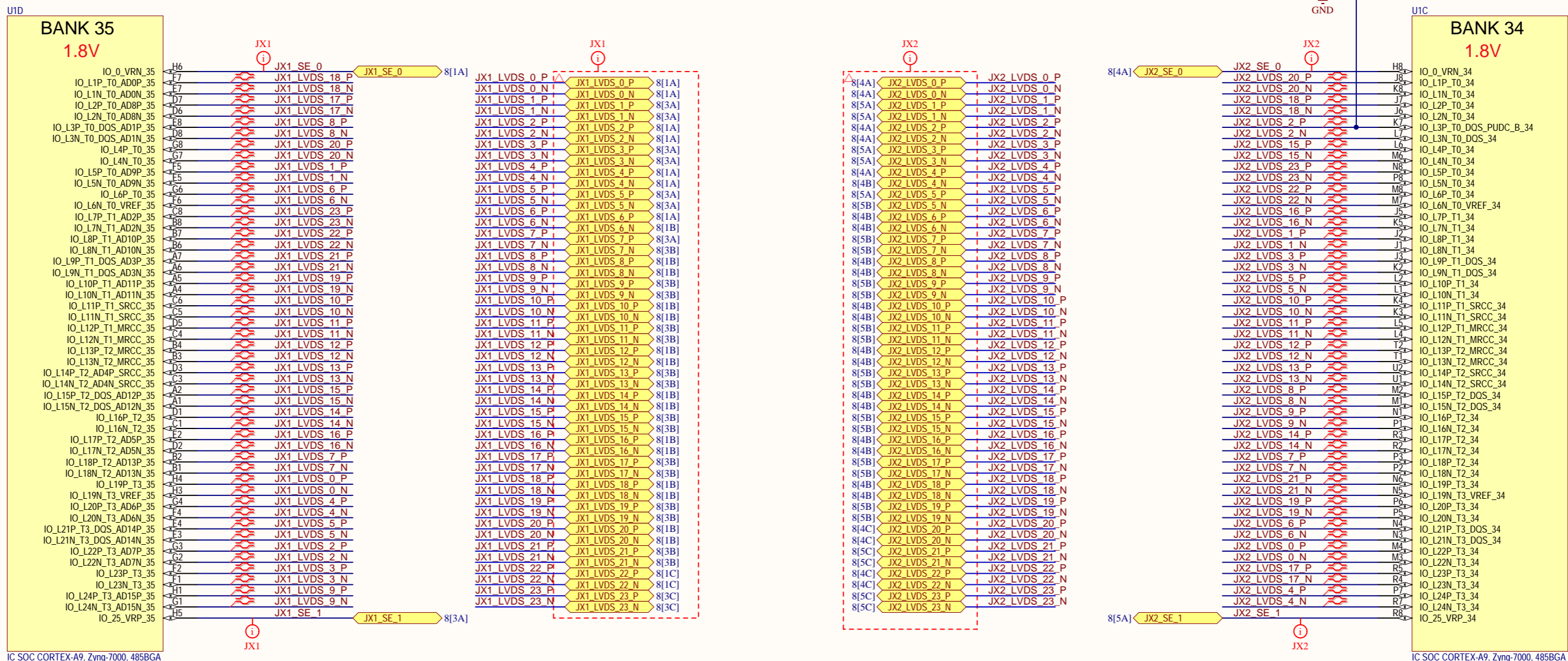
USB 2.0 OTG



Layout Note: USB_VBUS_OTG NET must be 500mA or more capable.

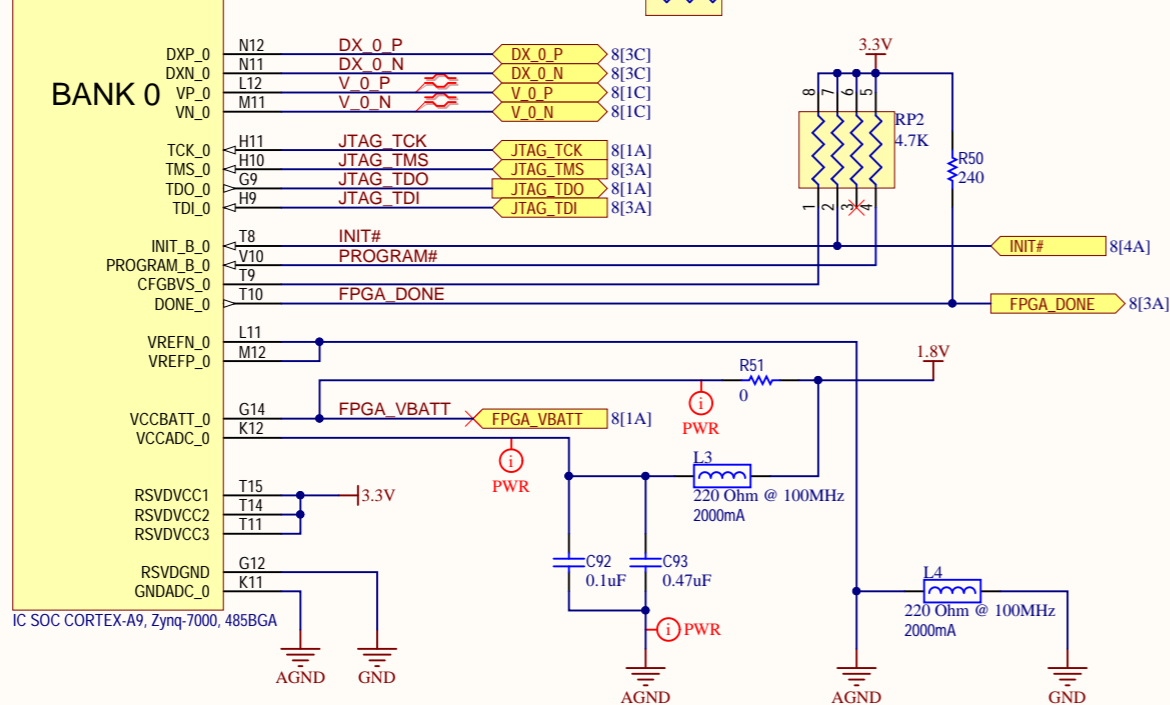
Layout Note: USB differential signal impedance target is 90 ohms.





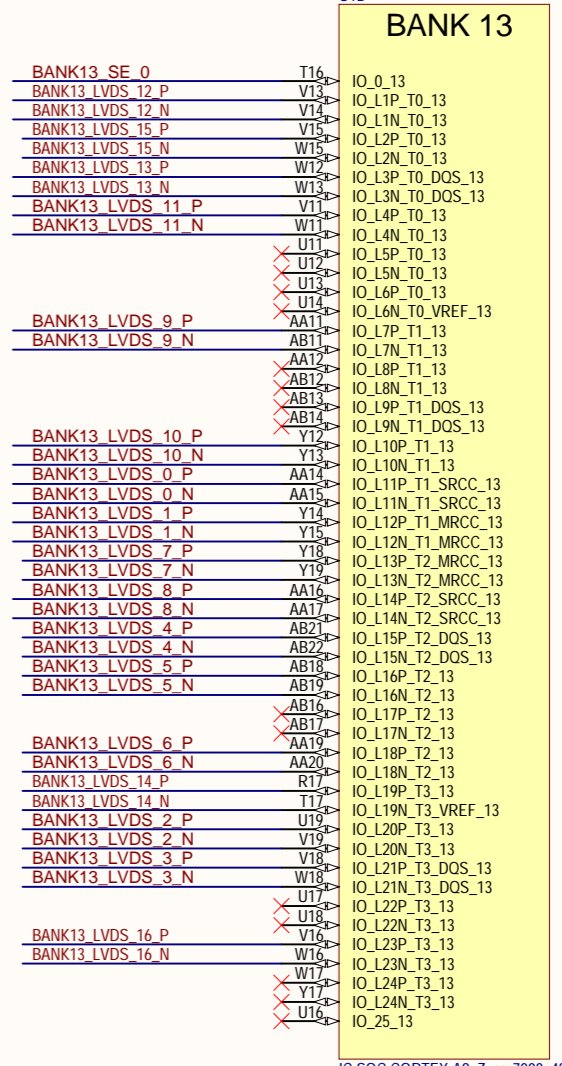
Default: pin 2-3, 1K

U1A



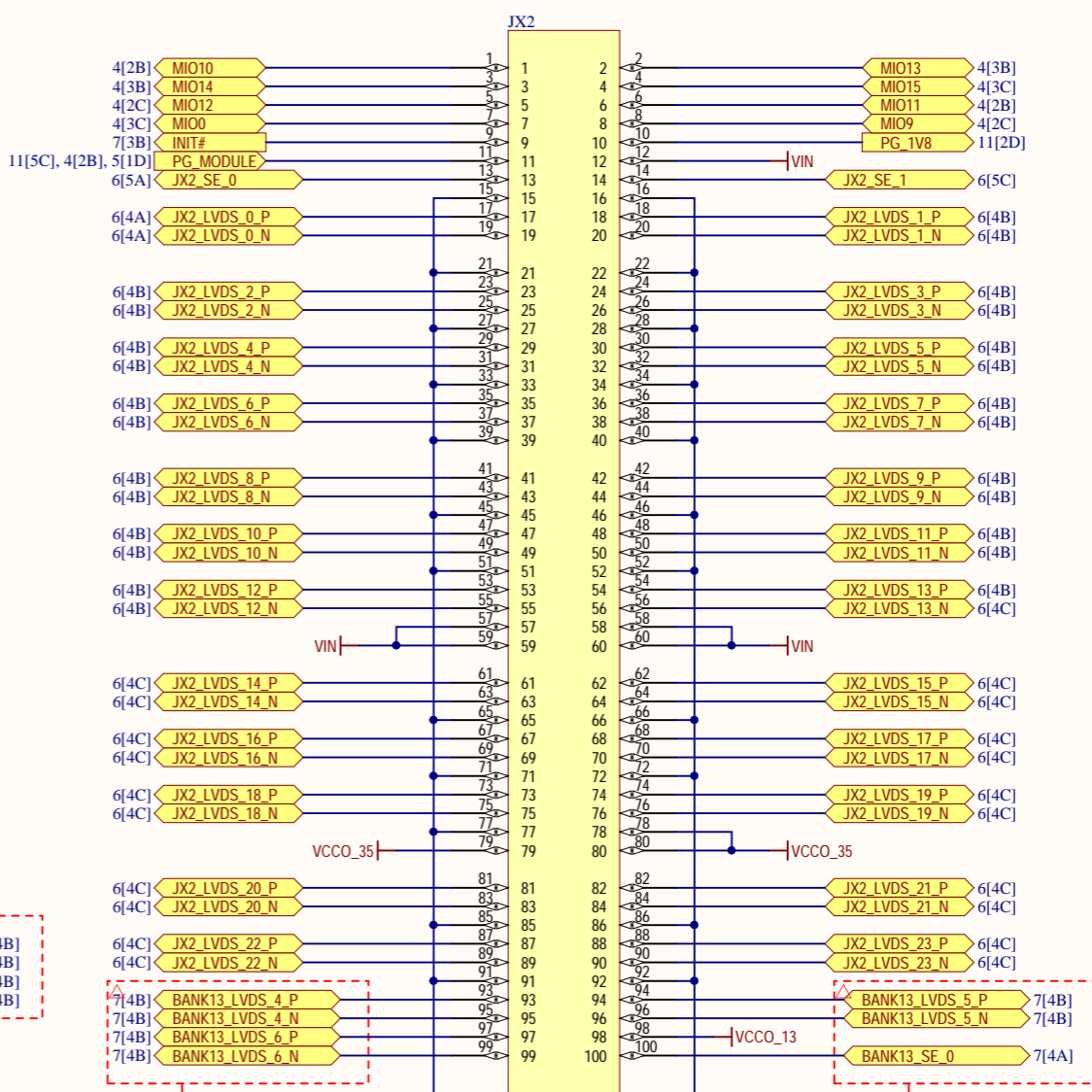
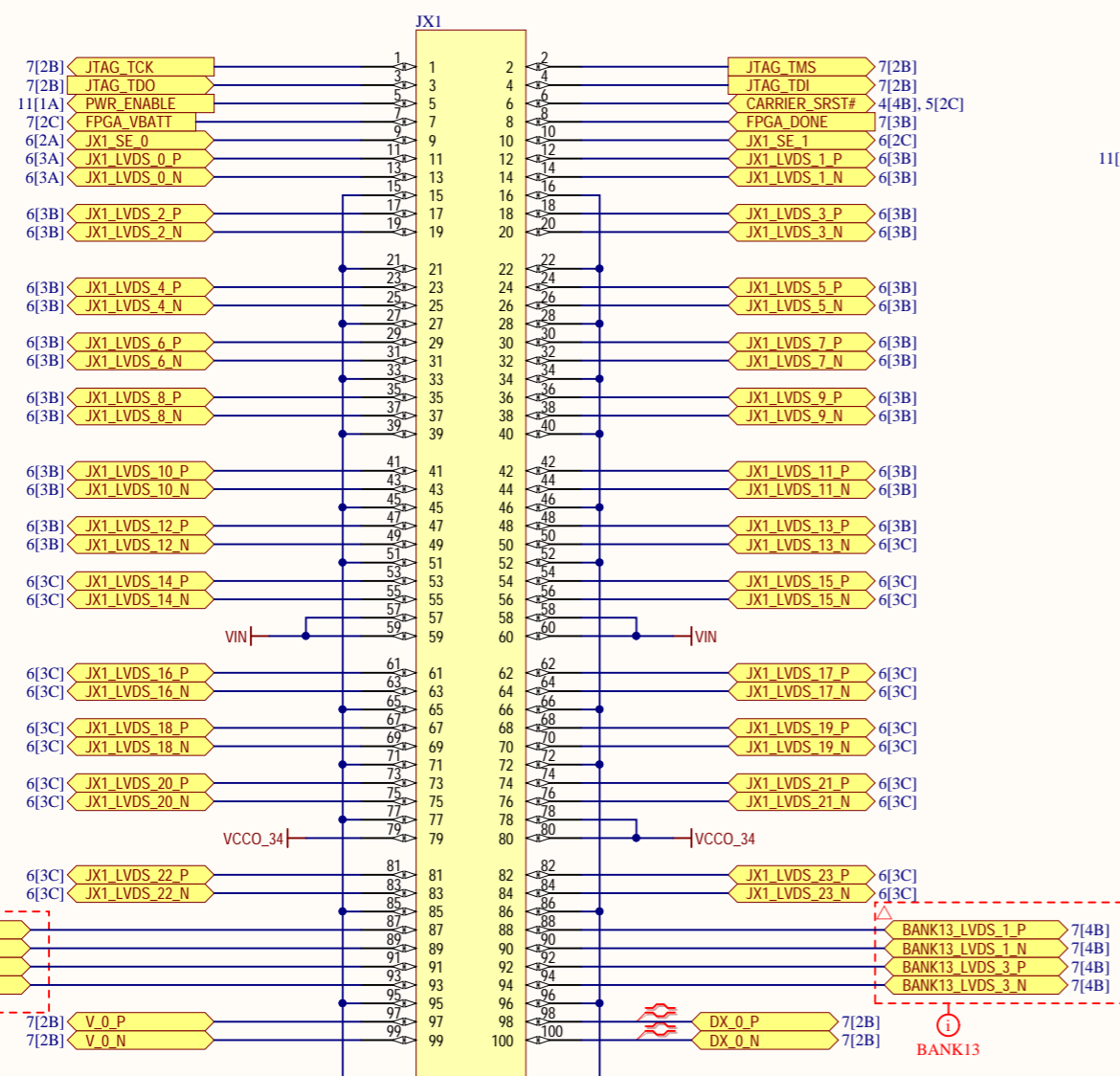
8[5C]	BANK13_SE_0	BANK13_SE_0	
8[1C]	BANK13_LVDS_0_P	BANK13_LVDS_0_P	
8[1C]	BANK13_LVDS_0_N	BANK13_LVDS_0_N	
8[3C]	BANK13_LVDS_1_P	BANK13_LVDS_1_P	
8[3C]	BANK13_LVDS_1_N	BANK13_LVDS_1_N	
9[3C]	BANK13_LVDS_7_P	BANK13_LVDS_7_P	
9[3C]	BANK13_LVDS_7_N	BANK13_LVDS_7_N	
9[4C]	BANK13_LVDS_8_P	BANK13_LVDS_8_P	
9[4C]	BANK13_LVDS_8_N	BANK13_LVDS_8_N	
8[1C]	BANK13_LVDS_2_P	BANK13_LVDS_2_P	
8[1C]	BANK13_LVDS_2_N	BANK13_LVDS_2_N	
9[3C]	BANK13_LVDS_9_P	BANK13_LVDS_9_P	
9[3C]	BANK13_LVDS_9_N	BANK13_LVDS_9_N	
9[4C]	BANK13_LVDS_10_P	BANK13_LVDS_10_P	
9[4C]	BANK13_LVDS_10_N	BANK13_LVDS_10_N	
9[3C]	BANK13_LVDS_11_P	BANK13_LVDS_11_P	
9[3C]	BANK13_LVDS_11_N	BANK13_LVDS_11_N	
8[3C]	BANK13_LVDS_3_P	BANK13_LVDS_3_P	
8[3C]	BANK13_LVDS_3_N	BANK13_LVDS_3_N	
8[4C]	BANK13_LVDS_4_P	BANK13_LVDS_4_P	
8[4C]	BANK13_LVDS_4_N	BANK13_LVDS_4_N	
8[5C]	BANK13_LVDS_5_P	BANK13_LVDS_5_P	
8[5C]	BANK13_LVDS_5_N	BANK13_LVDS_5_N	
8[4C]	BANK13_LVDS_6_P	BANK13_LVDS_6_P	
8[4C]	BANK13_LVDS_6_N	BANK13_LVDS_6_N	
9[4C]	BANK13_LVDS_12_P	BANK13_LVDS_12_P	
9[4C]	BANK13_LVDS_12_N	BANK13_LVDS_12_N	
9[3C]	BANK13_LVDS_13_P	BANK13_LVDS_13_P	
9[3C]	BANK13_LVDS_13_N	BANK13_LVDS_13_N	
9[4C]	BANK13_LVDS_14_P	BANK13_LVDS_14_P	
9[4C]	BANK13_LVDS_14_N	BANK13_LVDS_14_N	
9[3C]	BANK13_LVDS_15_P	BANK13_LVDS_15_P	
9[3C]	BANK13_LVDS_15_N	BANK13_LVDS_15_N	
9[4C]	BANK13_LVDS_16_P	BANK13_LVDS_16_P	
9[4C]	BANK13_LVDS_16_N	BANK13_LVDS_16_N	

U1B

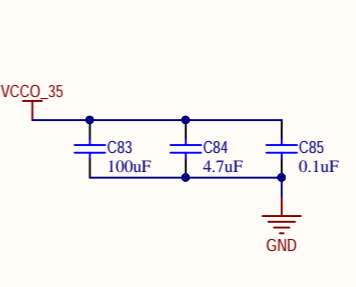
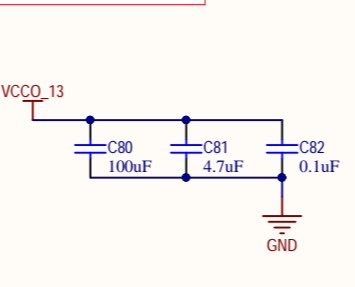
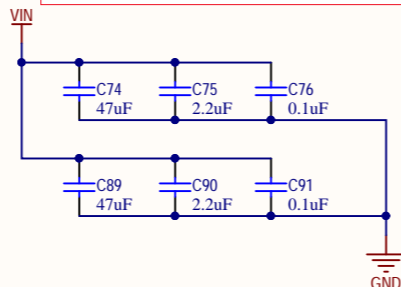
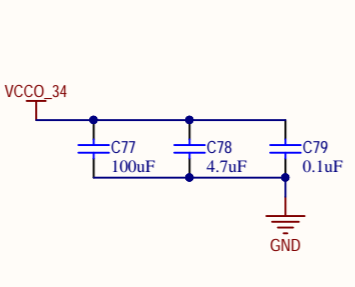
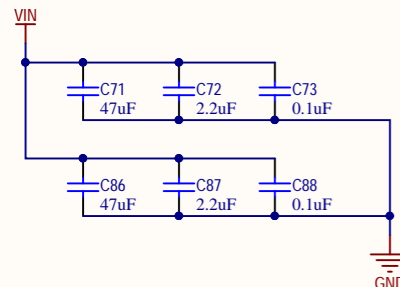


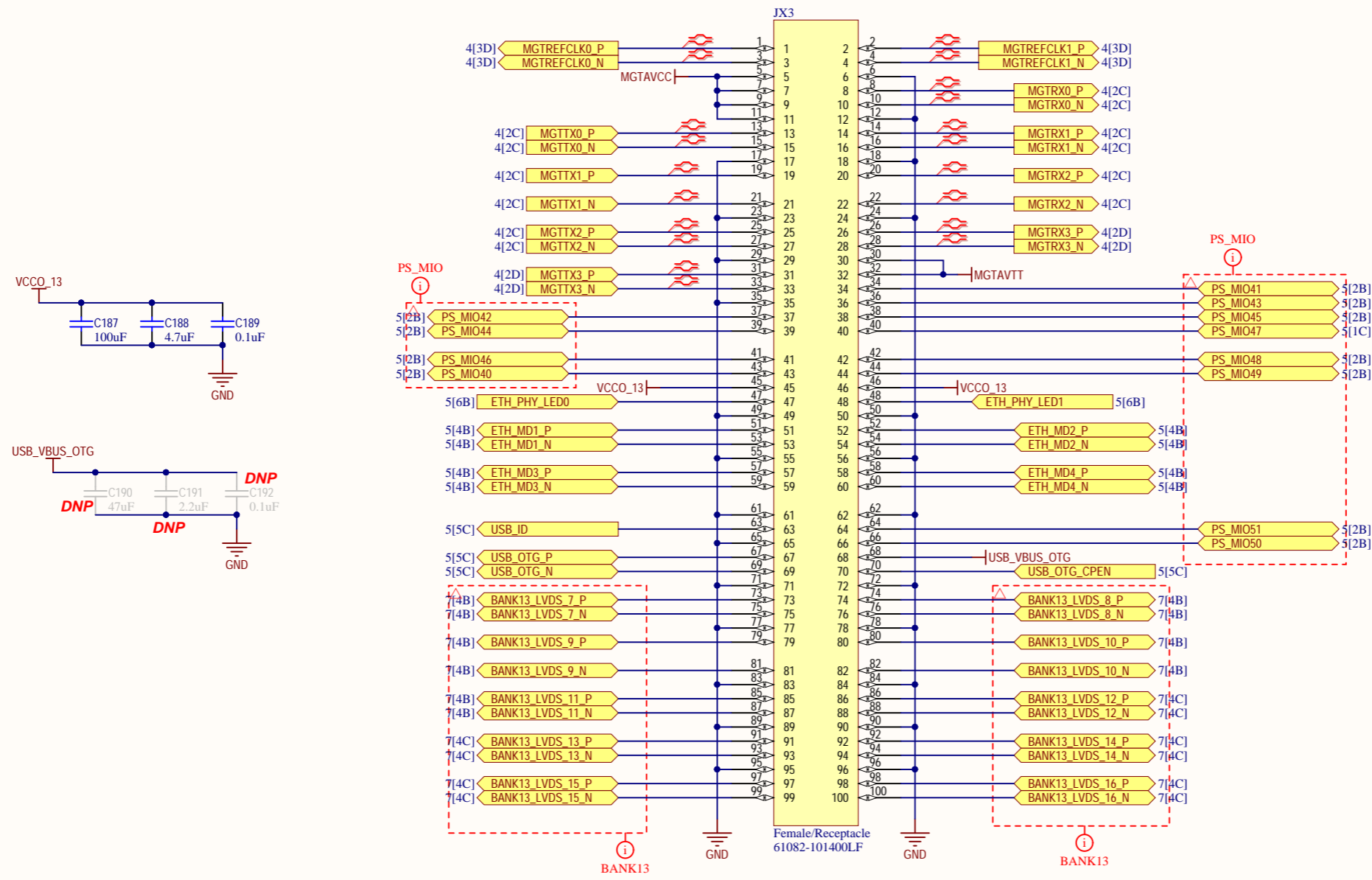
AVNET Avnet Engineering Services

Project Name:	PicoZed 7015/7030 SOM	PCB Rev:	BOM:	Variant:
Doc Num:	SCH-PZ2SOM	Date:	12/18/2017	Time: 11:06:38 AM
Sheet Title:	07 - BANK 0, BANK13, JTAG.SchDoc		Size:	Sheet: 7 of 12



WARNING!!!
 Bank 34 and Bank 35 are High Performance banks (7030 only) and will only accept 1.8V level signals. Failure to limit Bank 34 and 35 to 1.8V signals can damage the Zynq 7030 AP SoC.



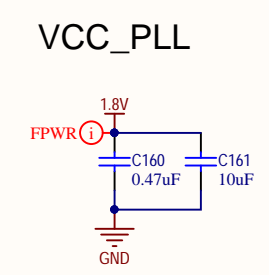
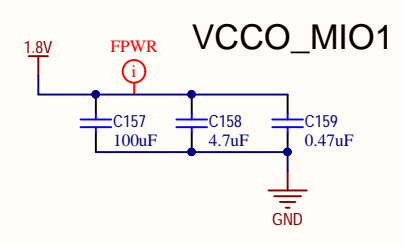
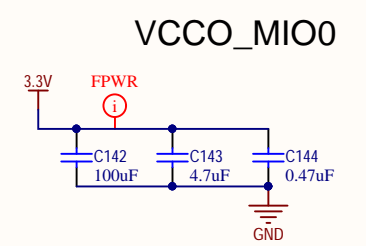
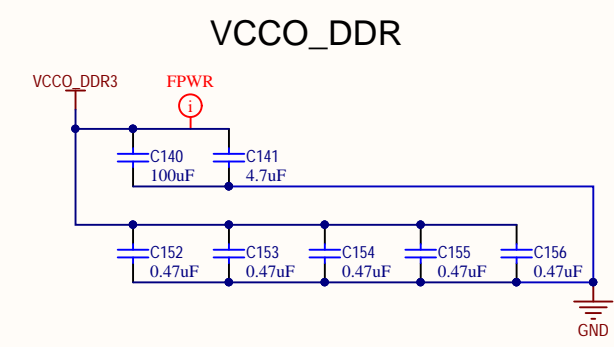
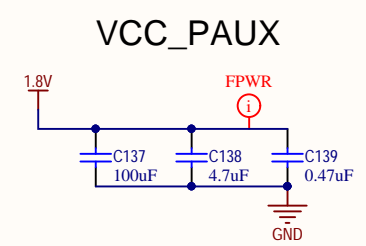
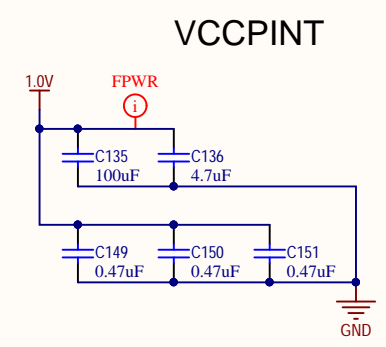
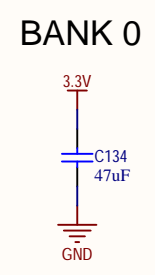
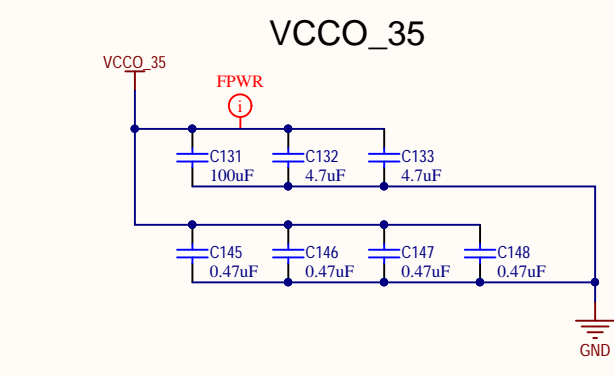
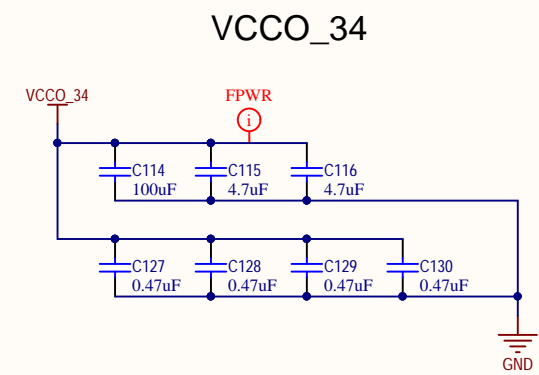
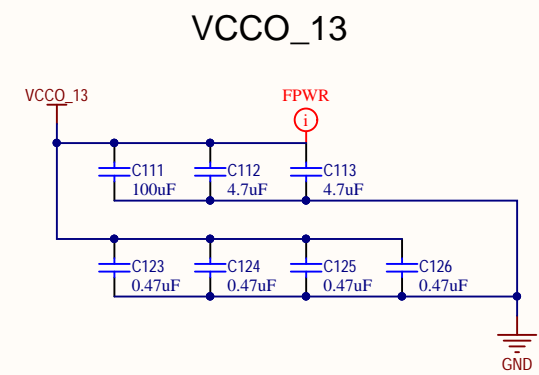
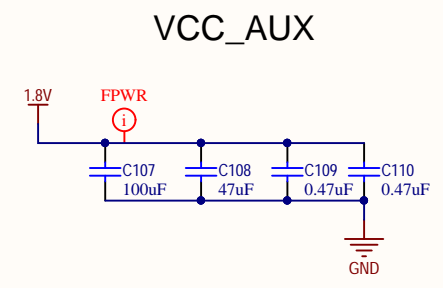
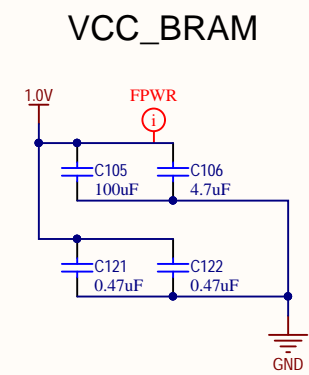
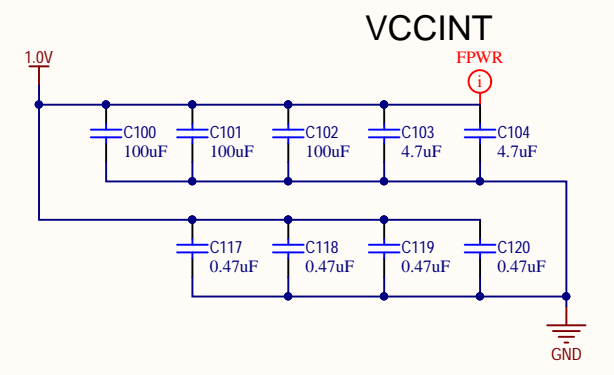
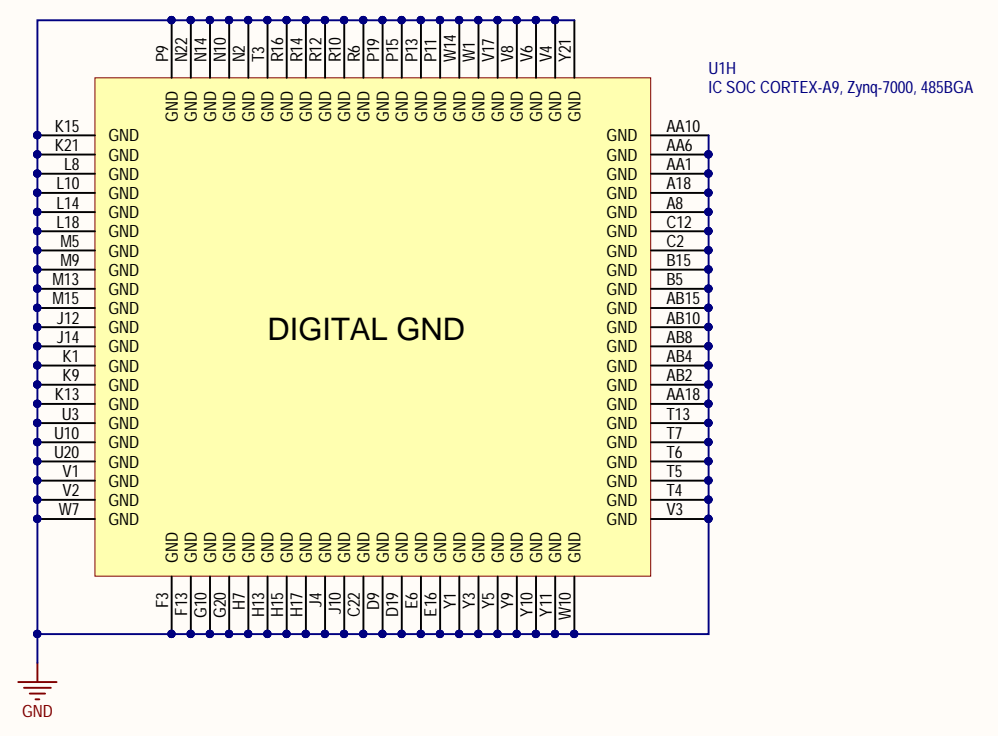
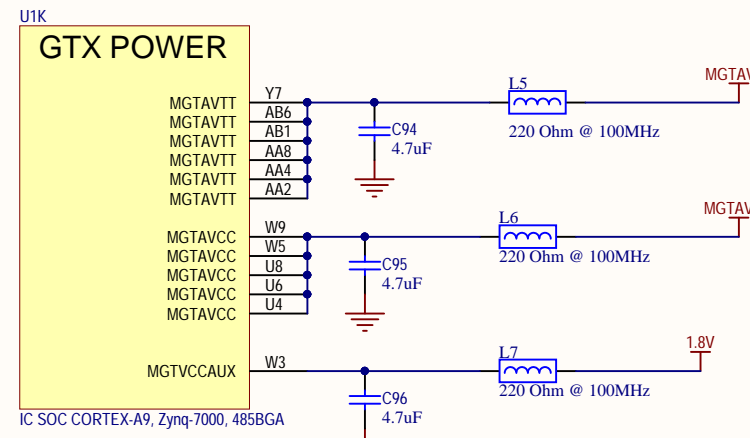
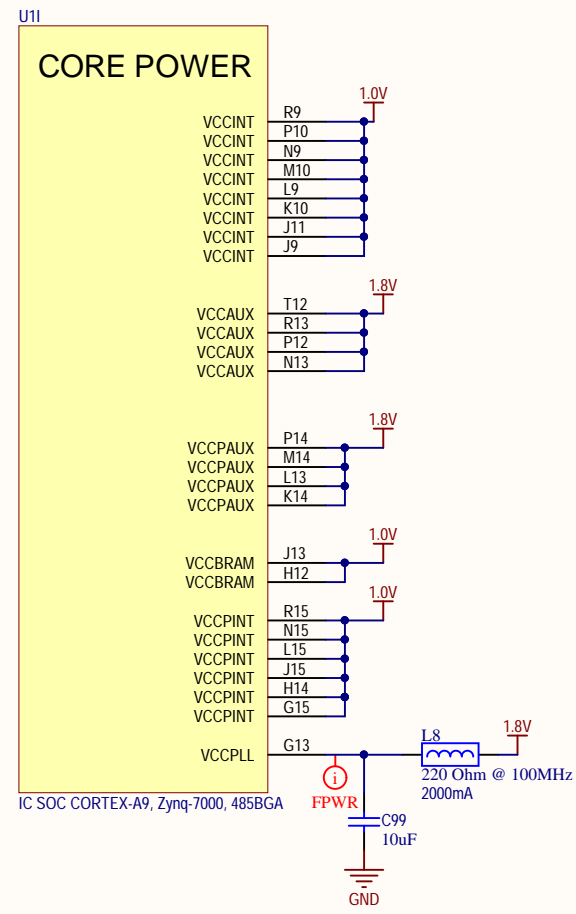
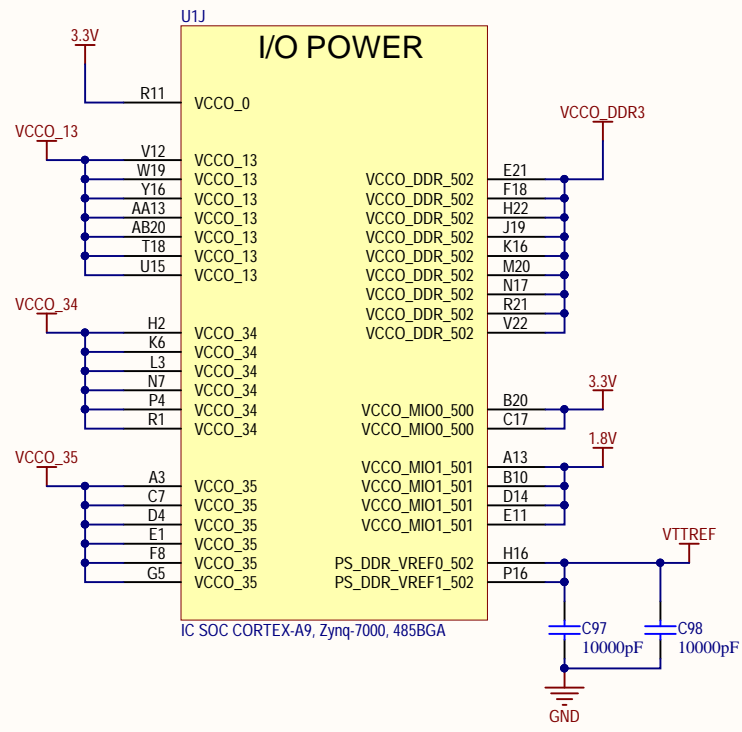


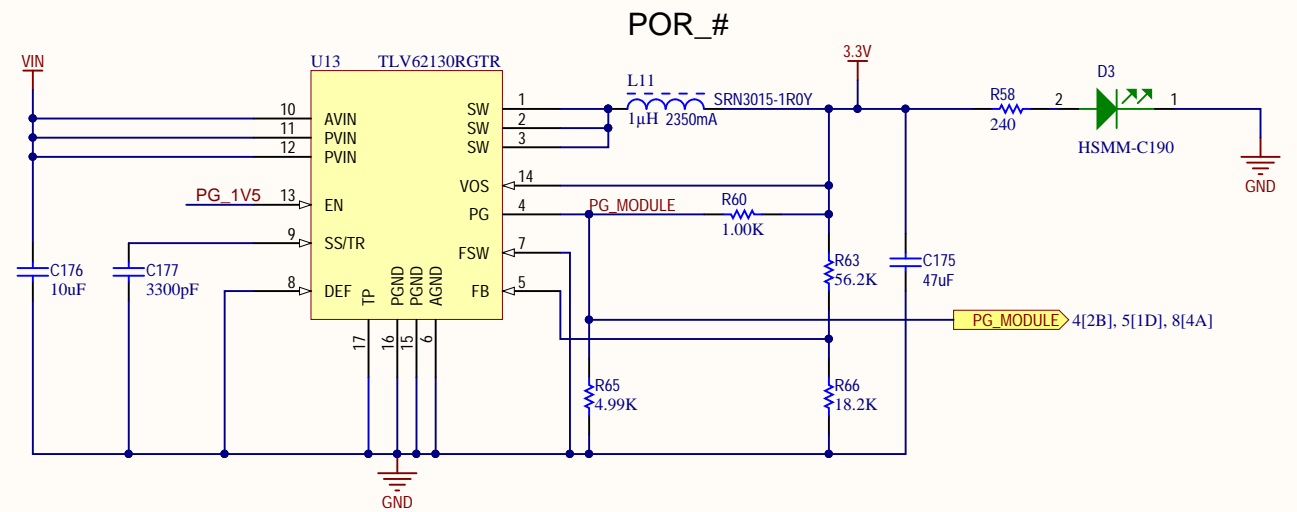
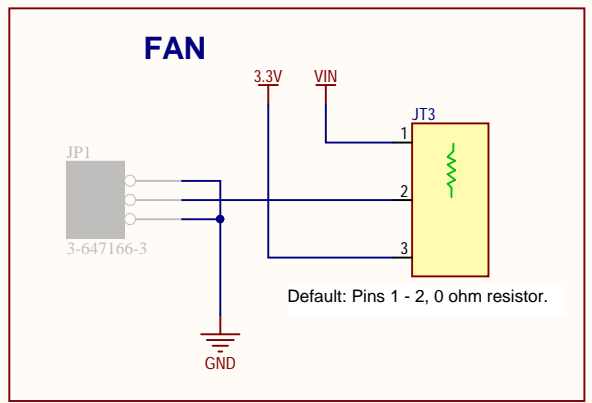
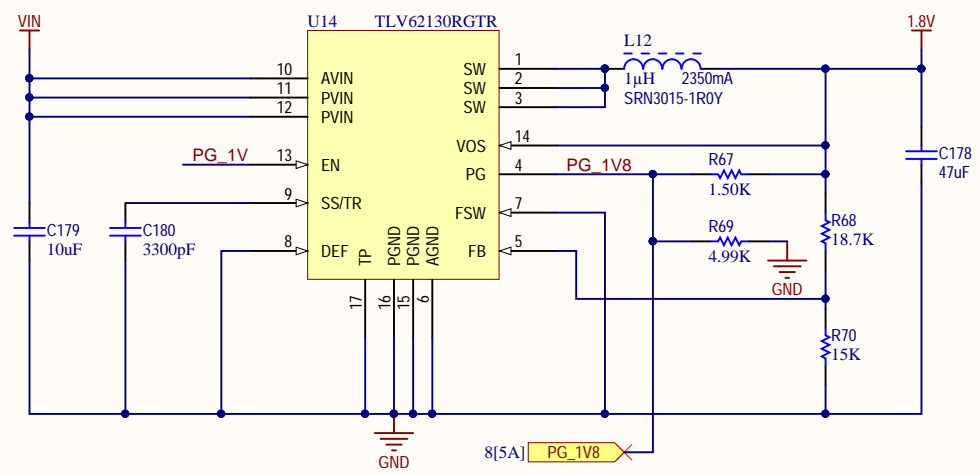
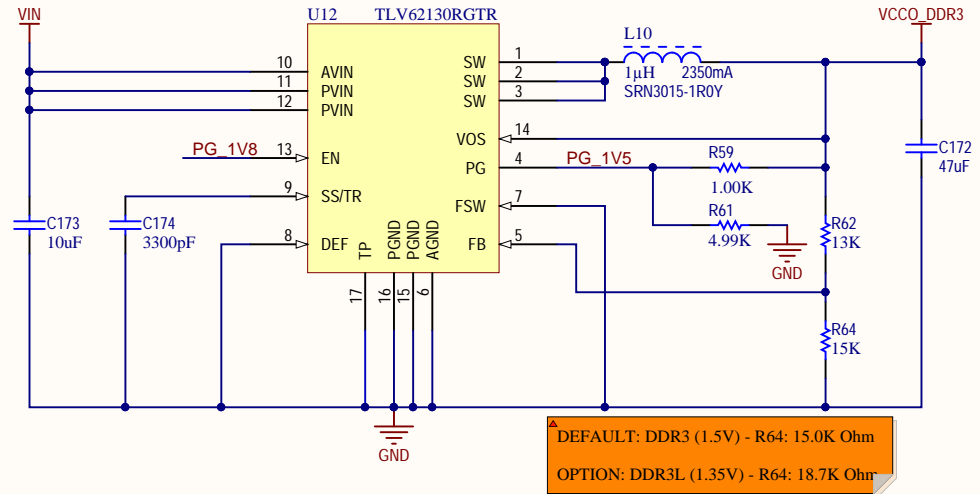
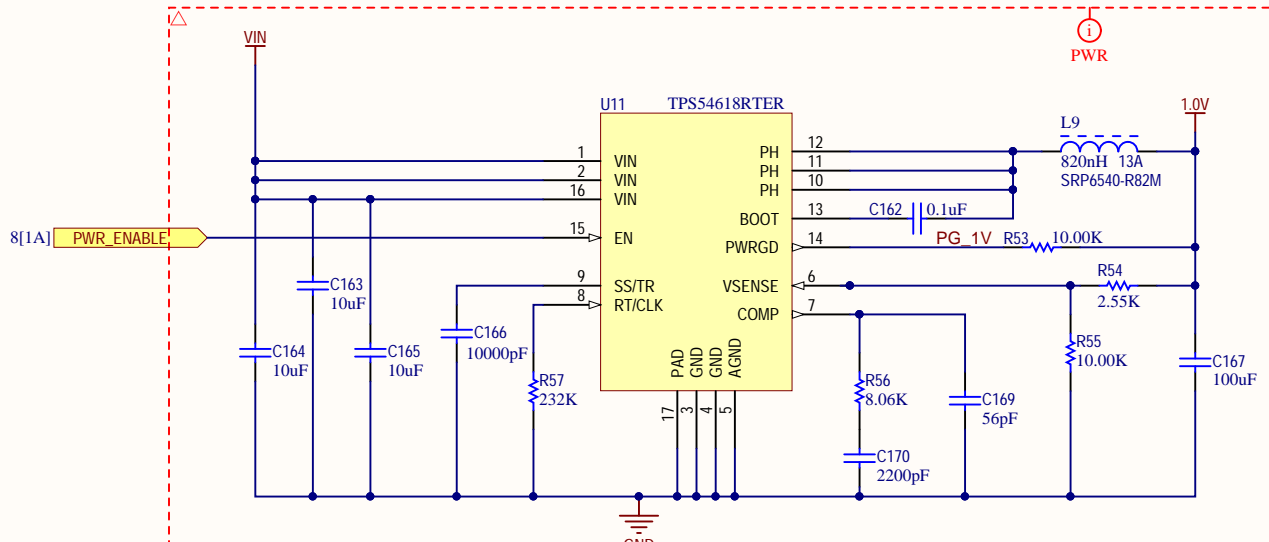
ZYNQ MIO POTENTIAL MAPPING OPTIONS:

SDIO INTERFACE
 PS_MIO40 - SD_CLK through a 40.2-ohm RES
 PS_MIO41 - SD_CMD
 PS_MIO42 - SD_D0
 PS_MIO43 - SD_D1
 PS_MIO44 - SD_D2
 PS_MIO45 - SD_D3
 PS_MIO46 - SD_CD

UART INTERFACE
 PS_MIO48 - UART_RXD (Tie to the TXD pin of a UART)
 PS_MIO49 - UART_TXD (Tie to the RXD pin of a UART)

USB INTERFACE
 PS_MIO40 - DATA
 PS_MIO41 - DIR
 PS_MIO42 - STP
 PS_MIO43 - NXT
 PS_MIO44 - DATA
 PS_MIO45 - DATA
 PS_MIO46 - DATA
 PS_MIO47 - DATA
 PS_MIO48 - CK
 PS_MIO49 - DATA
 PS_MIO50 - DATA
 PS_MIO51 - DATA





Revision History

Rev B

Original release

Rev C

- 1) Updated Block Diagram
- 2) Added shared circuit MIO47 to JX3 and ETHERNET RESET
- 3) Added RC time constant to ETHERNET RESET
- 4) DDR3L/DDR3 option note added
- 5) Renamed 1.5V and DDR3_0V75 power nets
- 6) Changed U4.2 connection from 1.8V to 3.3V
- 7) Changed JX1/JX2 connections to Zynq Bank 34/35 Clock Capable Pins

Rev D

- 1) U18, U19, JT1, JT5, and JT6 have been removed
- 2) U4, U15, and U17 part numbers changed
- 3) Moved C84,C96,C101,C107,C111,C114,C134,C140,C142,C15,C161,C183,R86, RP2, L3,L4,L5,L6,L7,L8, and U16 away from FPGA to allow for heatsink clearance
- 4) JT8 and JT9 added to allow Boot Mode to be hard wired with 0 Ohm Jumpers
- 5) JT6 Replaced with 4.99K Pulldown resistor

Rev E

- 1) Connected U17 Pin B3 to GND
- 2) Added Voltage Divider (R52, R96) and filter cap (C195) to U4 "VRI" pin
- 3) Added C199 and C200 to U15 Pin 3/5 (DDR3_VTT)
- 4) Added C196 to U15 Pin 2 (PVcc)
- 5) Changed C42 to 0.1uF Cap
- 6) Changed C39 to 4.7uF Cap

Mechanicals:




PCB

XXX-XXX-PCB-X

PCB PN (In Copper)

Assembly:

Label1
BD-XXXX-XXXXX-C
Label, Product

Label2

XXXXXXXX
Label, Serial Number

ESD1



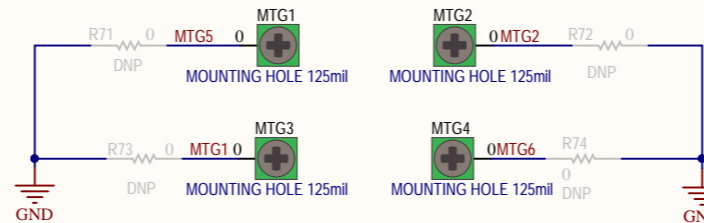
ESD Bag

Label_ESD1

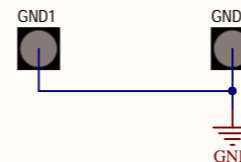


Label, ESD

PCB Mounting Holes



GND Test Points



AVNET Avnet Engineering Services

Project Name:	PicoZed 7015/7030 SOM	PCB Rev:	E	BOM:	01	Variant:	01
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